Abstract

Method for Polishing a Semiconductor Wafer

The invention relates to a method for polishing a semiconductor wafer, comprising polishing a surface of the semiconductor wafer using a polishing pad and in a first step with supply of a polishing agent slurry containing abrasives, subsequently ending the supply of the polishing agent slurry and in a second step with supply of a polishing agent solution having a pH value of greater than or equal to 12, which is free of solids, wherein the polishing pad used has a surface structure comprising elevations on the side that comes into contact with that surface of the semiconductor wafer which is to be polished, and wherein the polishing pad is free of substances with abrasive action.

No figure